

Blue LEDs

International Edition: DOI: 10.1002/anie.201502664 German Edition: DOI: 10.1002/ange.201502664

Blue Light: A Fascinating Journey (Nobel Lecture)**

Isamu Akasaki*

Blue LEDs · gallium nitride · laser diodes · light-emitting diodes · semiconductors

1. Introduction

"In the beginning there was light", emphasizes how closely light is tied to our lives. Light is indispensable for mankind and for many other creatures, and humans have pursued light sources since ancient times. Starting with flames, humans have developed electric light bulbs, fluorescent lamps, and then semiconductor light-emitting devices (light-emitting diodes (LEDs) and laser diodes (LDs)) in the second half of the last century. Although these light sources cover a wide wavelength range, the development of high-energy light sources has largely lagged behind. The development of an efficient blue LED had been a long-term dream for researchers worldwide, as it is indispensable for realizing LED-based full-color displays and general lighting applications

Drastic improvements in the crystal quality of gallium nitride (GaN)^[1] and the ability to control the conductivity in both p- and n-type nitride semiconductors^[2,3] in the late 1980s, have enabled the production of high-brightness GaN-based p-n junction blue/ultraviolet (UV) LEDs,^[2] high-performance blue-violet LDs,^[4] and many other novel devices. These successes triggered the opening of an entirely new field of electronics.

In this Review, I would like to describe the historical progress that led to the invention of the first p-n junction blue/ UV LED and related optical devices.

2. LED Research in the Early Days

In 1962, a red LED based on gallium arsenide phosphide (GaAsP) alloys was developed by N. Holonyak, Jr. and S. F. Bevacqua. [5] It was the first LED in the world to emit visible light. In 1968, a green LED was produced by R. A. Logan and his colleagues based on nitrogen-doped gallium phosphide (GaP:N). [6] At that time, however, there was no prospect of developing practical blue-light-emitting devices, which operate at the shortest wavelength in the visible spectrum and produce the highest energy.

The energy of photons from light-emitting semiconductor devices, such as LEDs, is approximately equal to the bandgap energy $(E_{\rm g})$ for the semiconductor that is being used. The wavelength of blue light is in the range 445–480 nanometers (nm), which is equivalent to a bandgap energy of 2.6–2.8 eV. There were therefore two requirements for creating blue-light-emitting devices.

Requirement [A] It is essential to use semiconductors with an $E_{\rm g}$ of approximately 2.6 eV or larger, equivalent to a wavelength of 480 nm or shorter (blue light). Semiconductors that have such a large $E_{\rm g}$ are referred to as "widebandgap semiconductors". In contrast, the $E_{\rm g}$ for the most commonly used semiconductor, silicon, is 1.1 eV.

Requirement [B] It is advantageous to use direct-bandgap semiconductors in which the momentum of electrons at the bottom of the conduction band is almost equal to that of holes at the top of the ground-state valance band (as shown in Figure 1), thus giving a high radiative recombination probability. In contrast, indirect-bandgap semiconductors exhibit a lower radiative recombination probability, because the momentum of these electrons and holes is different.

However, requirements [A] and [B] are not always sufficient conditions. To realize high-performance LEDs, it

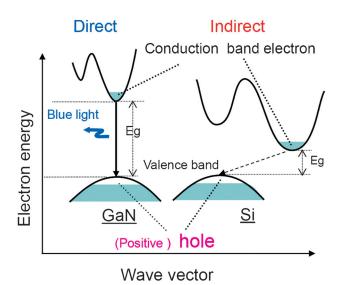


Figure 1. Band structures of GaN (direct transition type) and Si (indirect transition type).

[*] Prof. I. Akasaki

Meijo University

1-501 Shiogama-guchi, Tempaku-ku, Nagoya 468-8502 (Japan)

Nagoya University Akasaki Research Center Furo-cho, Chikusa-ku, Nagoya 464-8601 (Japan) E-mail: akasaki@ccmfs.meijo-u.ac.jp

[**] Copyright© The Nobel Foundation 2014. We thank the Nobel Foundation, Stockholm, for permission to print this lecture.



is essential to **(1)** grow high-quality single crystals, and **(2)** successfully produce p-n junctions (Figure 2).

Semiconductors that have more holes (electron deficiency) than electrons are referred to as p-type semiconductors, whereas those with more electrons than holes are referred to as n-type semiconductors. A p-n junction is an atomically continuous boundary between a p- and n-type semiconductor, and is necessary for the fabrication of devices



Isamu Akasaki was born on 30 January 1929 in Chiran-cho, Kagoshima prefecture, Japan. He graduated from Kyoto University in 1952 and obtained a Dr. Eng. in electronics from Nagoya University in 1964. In 1952, he joined Kobe Kogyo Corporation (now Fujitsu Ltd.), where he was a research staff member on a group studying electronic materials. Among his early contributions was the development of the manufacturing process for the fluorescent screens of cathode ray tubes of TVs (Kinescope) and of scintillators for β-rays. In 1959, he moved to

Nagoya University, where he held the positions of research associate and assistant professor before being appointed associate professor.

In 1964, he became head of the Basic Research Laboratory IV and then general manager of the Semiconductor Department at Matsushita Research Institute Tokyo, Inc. (MRIT), where he started research on optoelectronic materials and devices. He developed high-quality GaAs with the world's highest electron mobility by VPE (1968), and the brightest GaP red LED at that time (1970). In 1978, he and his group at MRIT developed the flip-chip-type GaN blue LED by hydride vapor-phase epitaxial growth (HVPE).

In 1981, he returned to Nagoya University as professor where he started afresh the growth of GaN by MOVPE. In 1986, he and his group succeeded in creating high-quality GaN by pioneering the low-temperature (LT) buffer layer technology. Using the high-quality GaN, they discovered low-resistive p-type GaN by doping with Mg and activating it by electron bombardment (LEEBI; 1989), produced the first GaN p-n junction blue/ UV LED(1989), and achieved conductivity control of n-type GaN by doping with Si (1990). In 1995 they achieved the first stimulated emission at 388 nm with electric current injection using a GaInN/GaN QW diode at room temperature, and in 1996 developed an LD with an AlGaN/ GaN/GaInN QW at 376 nm. In 2000 they showed theoretically the orientation dependence of the piezoelectric field and the existence of non-/ semipolar GaN crystals. These achievements have triggered today's worldwide efforts to grow those crystals and develop more efficient light emitters. Professor Akasaki is currently professor at Nagoya University and director of the Research Center for Nitride Semiconductor Core Technologies, Meijo University. He is life fellow of the IEEE. He received numerous honors and prizes, such as the Heinrich Welker Medal from the International Symposium on Compound Semiconductors (1995), the IEEE/LEOS Engineering Achievement Award (1995), the Laudise Prize from the International Organization for Crystal Growth (1998), the Jack A. Morton Award from the IEEE (1998), the Solid State Science & Technology Award from the Electrochemical Society (1999), the Toray Science & Technology Prize from the Toray Science Foundation (2000), the Outstanding Achievement Award from the Japan Society of Applied Physics (2002), the Order of the Rising Sun, Gold Rays with Neck Ribbon from the Japanese Government (2002), the Takeda Award from the Takeda Foundation (2002), the SSDM Award from the International Conference on Solid State Devices & Materials (2003), the Edison Medal from the IEEE (2011), the Order of Culture conferred by the Emperor of Japan in person (2011), the Imperial Prize and the Japan Academy Prize from the Japan Academy (2014), and together with Shuji Nakamura and Hiroshi Amano, the 2014 Nobel Prize

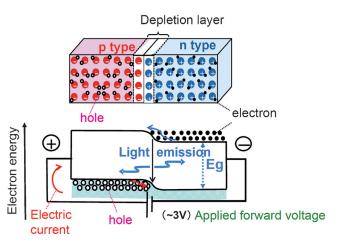


Figure 2. A schematic structure of a p-n junction LED.

such as highly efficient light emitters, solar cells, and transistors.

It is, however, extremely difficult to achieve (1) and (2) in wide-bandgap semiconductors, which prevented the development of high-performance blue-light-emitting devices for many years.

In the late 1960s and the 1970s, possible materials for bluelight-emitting devices included silicon carbide (6H-SiC) with an E_g of 3.0 eV, zinc selenide (ZnSe) with an E_g of 2.7 eV, and GaN with an $E_{\rm g}$ of 3.4 eV. Of those, SiC was the only widebandgap semiconductor for which p-n junctions could be created in those days, and some researchers attempted to develop blue LEDs based on this material.^[7] I had, however, absolutely no interest in this material for photonic-device applications because of its indirect band structure, which prevented efficient light emission. Meanwhile, although ZnSe and GaN were known to be direct-bandgap semiconductors (as summarized in Table 1), it was difficult to grow large bulk crystals of these materials, and no p-type crystals had been realized at that time. When it is difficult to produce large bulk crystals, epitaxial growth of single-crystal thin films is generally used. In vapor-phase epitaxial growth, source materials for crystal growth are provided to the substrate in the form of a gas. Growth then takes place in such a way that there is general alignment between the crystallographic axes

Table 1: A comparison between ZnSe and GaN.

ZnSe	GaN
2.7 eV	3.4 eV
direct	direct
straightforward	too difficult
GaAs	sapphire
0.26 %	16 %
not realized	at that time
many	few
low	high
	2.7 eV direct straightforward GaAs 0.26 % not realized many



of the grown crystals and the substrate. This method has been widely used in the growth of high-quality semiconductor with nanostructures. The terms "homoepitaxy" or "heteroepitaxy" is used when the grown crystal is the same as or different from the substrate crystal, respectively. In the latter case, it is necessary for the lattice constants of the two crystals to be as similar as possible to each other.

ZnSe emits bright light under excitation by an electron beam. Good-quality single-crystal ZnSe films can be grown using vapor-phase epitaxial growth on GaAs single-crystal substrates because the lattice constants are very similar. Thus, many researchers had been working on ZnSe, aiming to develop blue-light-emitting devices.

I myself, however, worried about the instability of ZnSe as a result of its low cohesive energy (bonding energy), and its poor crystallinity because of the low growth temperature that was required. In fact, a technique for p-type doping of ZnSe was developed later in 1988,^[8] and a lasing operation in a zinc cadmium selenide (ZnCdSe)/ZnSe heterostructure was demonstrated in 1991.^[9] However, the lifetime of ZnSe-based optical devices was found to be very short, and the researchers gave up attempting to develop this material further.

3. Brief History of GaN-Research

3.1. Early Attempts at Development of GaN Blue LED

From 1964 to 1981 I worked at the Matsushita Research Institute Tokyo, Inc. (MRIT). During these early stages of the research on Group III nitride semiconductor, I had an insight into the great potential of this material for blue-light-emitting devices, and yearned to pioneer a new field founded on the unique properties of nitrides, such as their toughness, wider direct energy gaps, and nontoxicity.

In 1967, I and Masafumi Hashimoto at MRIT grew aluminum nitride (AlN) crystals by vapor-phase reaction, and determined the angular frequencies of longitudinal and transverse optical phonons by fitting the calculated reflectivity to Reststrahlen (residual rays). It was very difficult, however, to use AlN as an electroluminescent material, because of its excessively large $E_{\rm g}$ of about 6.2 eV.

In the meantime (in 1969), H. P. Maruska and J. J. Tietjen successfully grew single-crystal GaN films on sapphire substrates using hydride-vapor-phase epitaxy (HVPE), and found that GaN is a direct-bandgap semiconductor with an $E_{\rm g}$ of 3.34 eV at room temperature (RT). [11] Then, in 1971, J. I. Pankove et al. developed GaN-based metal-insulator-semiconductor (MIS) blue LEDs [12] (Figure 4). R. Dingle et al. observed stimulated emission and laser action in single-crystal needles of GaN at 2–4 K. [13] These achievements intensified research and development of blue-light emitters based on GaN (period (A) in Figure 3).

In the mid-to-late 1970s, however, GaN researchers almost withdrew from the field, and interest in GaN-based devices declined (period (B) in Figure 3), because they could not grow high-quality semiconductor-grade GaN single crystals nor control the electrical conductivity of the material (realize p-type conduction in particular), both of which are

indispensable for producing high-performance light emitters based on a semiconductor p-n junction, although some researchers had continued to work on the basic and physical properties of GaN.^[14,15]

Besides, at that time, theoretical studies indicated the impossibility of achieving p-type conduction in wide-bandgap semiconductors such as GaN and ZnSe because of the "self-compensation effect".^[16]

Despite this stalemate, I started to work on the growth of GaN single-crystal films by molecular-beam epitaxy (MBE) in 1973, and then by HVPE in 1975, aiming at the development of GaN-based p-n junction LEDs and LDs. In 1978, by utilizing HVPE, my group at MRIT developed a MIS-type GaN blue LED with a unique device structure of highly n-type (n⁺) GaN pillars buried in a thick n-GaN layer on top of a thin insulating GaN (i-GaN) layer (as shown in Figure 4). The n⁺ pillars could be used as cathodes, which greatly simplified the fabrication of MIS-type LEDs. [17,18] The external efficiency was 0.12 %, which was the highest ever reported at that time. However, as a result of the use of a MIS structure, the operating voltage was high and the brightness was low, in contrast to the p-n junction LEDs we invented later. [2]

3.2. Reconsideration of Growth Technology

In parallel with the work described above, [18] I also recognized the great potential of GaN as a blue luminescent material when I found tiny but high-quality crystallites embedded in HVPE-grown crystals containing many cracks and pits under the microscope. I was intuitively convinced that it would be possible to achieve conductivity control (even p-type GaN) if this kind of quality could be obtained over an entire wafer. Thus, in 1978, I made up my mind to go back one more time to the beginning, that is, "crystal growth", which is an interdisciplinary science and essential for the realization of quantum devices with nanostructure. I think of this decision as a major turning point in not only my own GaN research, but also GaN research and development throughout the world, which had been stagnating at that time (period (B) in Figure 3).

It is known that the quality of crystal is greatly affected by the nature of the chemical reactions involved in their production, in other words, the growth method and conditions. Hence, the choice of growth method was critical for determining the future of the research. Epitaxial GaN can be grown by MBE, HVPE-, or metalorganic vapor-phase epitaxy (MOVPE), the latter of which is also known as metalorganic chemical vapor deposition (MOCVD; as described in Table 2).

On the basis of my experience in crystal growth, I realized that MBE was prone to introducing a nitrogen deficiency and the growth rate was very slow at that time. In the case of HVPE, the crystal quality was degraded by appreciable reverse reactions, and the growth rate was too high to fabricate devices with layer thicknesses in the order of nanometers. Therefore, these methods were not suitable for producing well-controlled devices based on high-quality GaN crystals



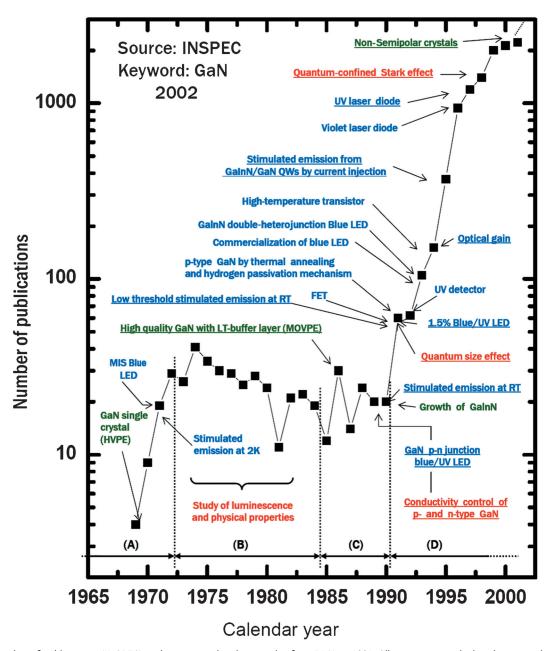


Figure 3. Number of publications (INSPEC) and activities related to nitrides from 1969 to 2002. All events are marked in the years when they were first achieved. Most of the important results were achieved by MOVPE using an LT buffer layer after 1986. It is clear that the start of the steep increase in the number of publications and accomplishments is due to the key inventions (high-quality GaN, p- and n-type conductivity control, and p-n junction blue/UV LED) in the late 1980s and 1990. Underlined achievements are studies done by Akasaki's group. Green: Crystal Growth, Blue: Devices, Red: Conductivity Control and Physics.

MOVPE, which was first applied to the growth of GaN by H. M. Manasevit et al. in 1971, [19] but almost never employed for this purpose thereafter, seemed to be more suitable, because of the absence of reverse reactions. Furthermore, the composition of alloys, such as aluminum gallium nitride (AlGaN) and gallium indium nitride (GaInN), and the level of impurity doping could be readily controlled by varying the flow rates of the source gases in MOVPE. Thus, in 1979, I decided to adopt MOVPE as the optimal method for GaN crystal growth. It was a crucial decision. As for the substrate

for GaN growth, I tentatively (until a more suitable substrate would become available) chose the c-face of sapphire as before, because it was stable even under the harsh MOVPE conditions, namely a temperature above 1000°C and an ammonia (NH₃) atmosphere, and is similar to GaN in terms of crystallographic symmetry.

The fact that, even today, GaN-based crystals and devices are mainly grown on sapphire substrates by MOVPE is a clear indication that my choices were not wrong.



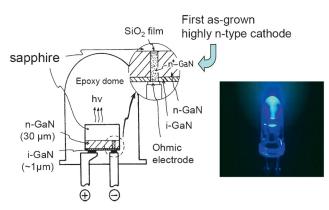


Figure 4. A schematic and a photograph of a MIS-type GaN blue LED (developed in 1978).

Table 2: Crystal growth methods for GaN.

Molecular-Beam Epitaxy (MBE)

I. Akasaki (1974) (in Japanese).

Ga (g) + NH₃ (g) = GaN (s) + $\frac{3}{2}$ H₂ (g)

Issues: Prone to nitrogen deficiency, Slow growth rate (at that time)

Hydride Vapor-Phase Epitaxy (HVPE)

H. P. Maruska and J. J. Tietjen (1969).

GaCl (g) + NH₃ (g) = GaN (s) + HCl (g) + H₂ (g)

Issues: Susceptible to reverse reactions, Too fast growth rate

Metalorganic Vapor-Phase Epitaxy (MOVPE)

H. M. Manasevit et al. (1971).

Ga(CH₃)₃ (g) + NH₃ (g) \rightarrow GaN (s) + 3CH₄ (g)

Advantages:

No reverse reactions

Easy to control growth rate, alloy composition, and impurity doping

4. Creation of GaN Single Crystals with Excellent Quality

4.1. Development of the Low-Temperature Buffer-Layer Technology in MOVPE

After making these crucial decisions, I returned to my old "nest", Nagoya University, where I started anew to drastically improve the crystal quality of GaN grown by MOVPE in collaboration with my graduate students Yasuo Koide and Hiroshi Amano, who put a lot of efforts into the growth of the crystals. Even with the MOVPE method, however, it was not easy for us to develop homogeneous GaN films. After many trials and errors, we made drastic innovations and improvements to the reactor tube and growth conditions.

The first improvement was that Koide mixed organometallic compounds such as trimethylgallium (TMGa) (and trimethylaluminum (TMAl) in the case of AlGaN growth) with NH₃ and hydrogen (H₂) gas as a carrier right in front of the opening of the reactor tube, and blew this mixture through a gas delivery tube onto a substrate that was inclined at a 45° angle rather than being placed horizontally as in previous attempts (as shown in Figure 5). We also drastically increased the flow velocity of the gases in the reactor tube from only 2 cm s⁻¹ to approximately 110 cm s⁻¹. We were thus able to

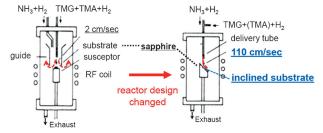


Figure 5. Schematic drawings of the reactor part of the MOVPE system before and after the reactor design was changed.

reduce the formation of adducts of NH₃ and the organometallic sources, and to suppress convective gas flows on the high-temperature substrate, which resulted in a uniform gas flow and the production of homogeneous GaN films. Even though the film thickness was fairly constant over the entire wafer, this did not mean that there were no pits or cracks. There was also no substantial improvement in the electrical or optical properties, which suggested the presence of lattice defects and unintentionally incorporated impurities.

I suspected that, for the most part, this was a result of the large interfacial free energy between GaN and sapphire caused by the huge lattice mismatch of 16% between the two crystals (as in Figure 6). In fact, for epitaxial growth of

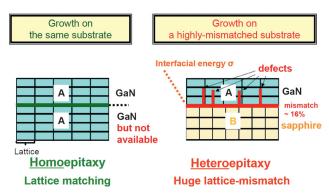


Figure 6. Homoepitaxy (GaN on GaN) and heteroepitaxy (GaN on sapphire).

semiconductor crystals, it was considered to be "gospel" to have complete lattice matching as in the case of GaAs growth on a GaAs substrate. For heteroepitaxial growth, even a mismatch of about 1% would make it difficult to grow crystals of a good quality.

To overcome this issue, we developed the low-temperature (LT) buffer layer technology in 1985. [1,18,20] Specifically, this is a method for producing a thin buffer layer from a material with physical properties similar to those of GaN and sapphire with a thickness of 20–50 nm, which is thin enough not to interfere with the transmission of crystallographic information from the substrate to the epitaxial layer (as shown in Figure 7). The temperature for the deposition of the buffer layer might be several 100 °C, which is considerably lower than the typical growth temperature for single-crystal GaN. The temperature would then be raised to that required



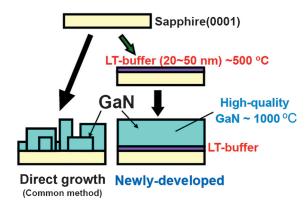


Figure 7. Low-temperature buffer layer technology for producing high-quality GaN.

for epitaxy growth of GaN single crystal, which is approximately 1000 °C.

The idea is to have a soft or flexible thin layer without a rigid structure, such as that of a single crystal, inserted between the substrate and the GaN film. The purpose of the buffer layer is to create conditions as close as possible to those for homoepitaxy, where no interfacial free energy exists in principle. For the buffer layer materials, I considered AlN, GaN, zinc oxide (ZnO), and SiC. First, we tried AlN, with which I was already familiar. [10]

In addition to the first improvement by Koide, Amano used the LT-AlN buffer layer technology combined with a further accelerated gas-flow velocity of about 430 cm s⁻¹. By using this approach, in 1985, we eventually succeeded in growing the world's first extremely high-quality (semiconductor grade) epitaxial GaN film, [1] which has been the drastic innovation in the GaN research.

Scanning electron micrographs (SEM) of surfaces of GaN films grown on a sapphire substrate showed the surface morphology of the films to be markedly improved by the LT-AlN buffer layer, [1,22] as shown in Figure 8. The GaN film had a specular surface with no pits or cracks, and was so transparent that letters written on the underlying paper could be clearly seen (as shown in Figure 8c).

Cross-sectional transmission electron microscopy (TEM) showed that the density of crystal defects, such as dislocations, markedly decreased with the use of the LT-AlN buffer layer. [21] X-ray diffraction profiles also showed that the crystal quality of GaN was significantly improved by this method. [1,22] The residual donor (electron) concentration for GaN grown with the LT-AlN buffer layer decreased to the order of 10^{17} cm⁻³, which is more than two orders of magnitude lower than that for GaN grown without the LT-AlN buffer layer. [22] Soon after, the electron concentration was further reduced to less than 10^{15} cm⁻³. [18] Simultaneously, the electron mobility markedly increased to several hundred cm² V⁻¹ s⁻¹. [22,23]

Figure 9 shows that near-band-edge emission predominated the photoluminescence (PL) spectrum of the undoped GaN grown with the LT-AlN buffer layer, whereas deep-level-related yellow emission was the major emission from GaN grown without the LT-AlN buffer layer. [22] In the spectrum from another GaN film grown with a LT-AlN buffer layer, free exciton lines (FE^A and FE^B) and impurity-

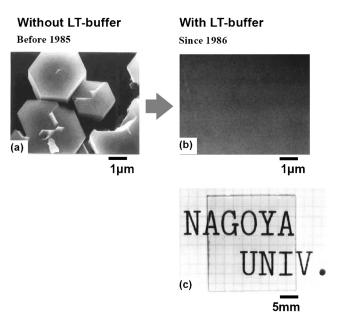


Figure 8. Scanning electron micrographs of GaN on sapphire a) without LT buffer layer and b) with LT buffer layer. c) Photograph of a specular and transparent GaN film grown on sapphire with LT buffer layer.

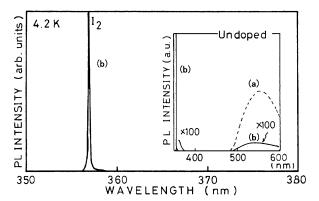


Figure 9. Photoluminescence spectra (4.2 K) of undoped GaN films on sapphire substrates a) without (dashed line in the inset), and b) with LT buffer layer (solid line).

bound excitons (DBE and ABE) were clearly observed, showing that the crystal quality was drastically improved. By using the LT-AlN buffer layer deposited under optimum conditions, not only the crystal quality but also the electrical and luminescence properties of GaN were greatly improved, [1,22-24] as already seen in Figures 8 and 9.

The thrill I felt when I finally saw transparent and specular GaN crystals is simply unforgettable. It was something that I had dreamt of realizing ever since the early 1970s.

This technology was an epochal concept that provided control over the growth of GaN, thus dramatically improving the quality of GaN and its alloys, which in turn resulted in conductivity control for both p- and n-type nitrides, p-n junction blue-light-emitting device applications, and a revival in the materials science of nitrides.

In 1991, S. Nakamura reported that a LT-GaN buffer layer had the same effect as a LT-AlN buffer layer. [25]



Today, this LT buffer layer technology in MOVPE has become the standard approach to growing high-quality GaN and nitride alloys.

4.2. Model for the Growth Mode

In order to clarify the role of the LT-AlN buffer layer, different stages of GaN growth on the c-face of sapphire were studied by SEM and reflection high-energy electron diffraction (RHEED). [21–23] Figure 10 (taken by Kazumasa Hira-

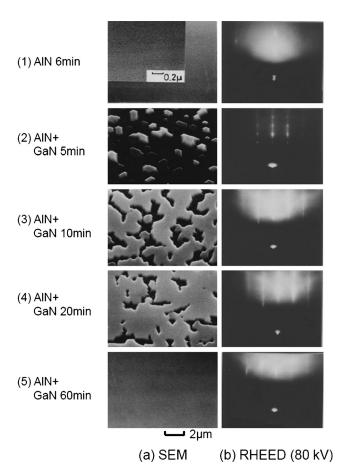


Figure 10. a) Scanning electron micrographs and b) reflection highenergy electron diffraction patterns during the GaN growth on sapphire with LT buffer layer.

matsu et al.) shows a) SEM images of the changes in surface morphologies during the growth and b) the corresponding RHEED patterns from the same region. Image (1) in Figure 10 a was obtained for the deposited AlN buffer layer, whose thickness was about 50 nm; the layer appears uniform and featureless. However, the image in the inset, which was taken at high magnification, appears to show fine particles with sizes of several nanometers, which seem to be embedded in the futureless structure. The corresponding RHEED pattern in Figure 10b shows somewhat diffuse spots together with a halo-like pattern, which is in agreement with the SEM results. The AlN buffer layer is thought to consist of fine crystallites in an amorphous matrix. After 5 min of growth,

many truncated hexagonal pyramidal mesas (trapezoidal crystals) have formed (see image (2) in Figure 10a). Two-dimensional lateral growth then occurs for a certain period, as shown in image (3). Subsequently, quasi-lateral growth dominates when the GaN film reaches a certain thickness, as seen in image (4). Finally, the entire substrate is covered by a flat GaN film, as seen in image (5). In Figure 10b, RHEED pattern (2), obtained after 5 min of growth, is spot-like, indicating that the GaN islands are three-dimensional. Subsequently, the pattern becomes streaky, as the surface becomes flatter.

Figure 11 shows a low-magnification cross-sectional bright-field TEM image of a wide region of a GaN film grown using a LT-AlN buffer layer.^[21] It can be seen that three

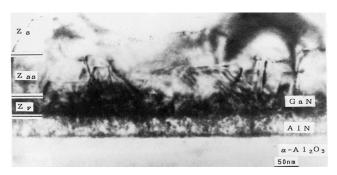


Figure 11. Bright-field image of GaN on sapphire with LT-AIN buffer layer by cross-sectional TEM.

zones with different microstructures exist within the GaN layer. The zone nearest to the AlN buffer layer has fine image contrasts because of a number of defects. Consequently, this zone is referred to as the "faulted zone" ($Z_{\rm F}$) and is about 50 nm thick. Above the faulted zone, there is another zone, which contains a number of trapezoid crystals, corresponding to the truncated hexagonal pyramidal GaN islands observed by SEM, as shown in image (3) in Figure 10a. As the defect density in this zone is much lower than that in the faulted zone, it is called the "semi-sound zone" ($Z_{\rm ss}$), and is about 150 nm thick. The upper zones is referred to as the "sound zone" ($Z_{\rm s}$), as it contains only a small number of defects. In the sound zone, the defect density decreases abruptly for GaN layers thicker than about 300 nm, resulting in high-quality uniform GaN.

Figure 12 shows a dark-field cross-sectional TEM image with a little higher magnification in order to clarify the microstructure of the AlN layer and the different zones in the GaN layer. The image contrasts in the figure show that the AlN layer is composed of columnar fine crystals such as frost columns. The diameter is in the order of 10 nm, which corresponds to the front of the columnar crystals. The AlN layer has an amorphous structure at the deposition temperature, as shown in Figure 10(1). However, as the temperature is ramped from the low AlN deposition temperature to the GaN epitaxial temperature of about 1000 °C, solid-phase regrowth occurs, and a fine columnar structure forms in the AlN. Similar contrast is seen in the faulted zone of the GaN, which suggests that GaN in the faulted zone is also composed



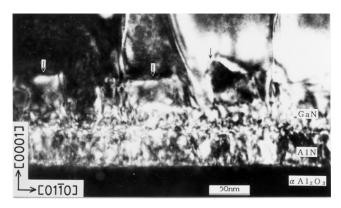


Figure 12. Dark field image of GaN on sapphire with LT-AIN buffer layer by cross-sectional TEM.

of columnar fine crystals. It is likely that each GaN column from a GaN nucleus has formed on top of a columnar AlN crystal. Therefore, it is thought that high-density nucleation of GaN occurs as a result of the much higher density of AlN columns, as described in Figure 13(1)–(3), compared to the case where GaN is grown directly on a sapphire substrate, as shown in Figure 8a.

Figure 13 shows the proposed growth model for a GaN film on a c-face sapphire substrate with a LT-AlN buffer layer. Each fine GaN crystal begins to grow along the *c*-axis, forming a columnar structure. Each of the columns is slightly

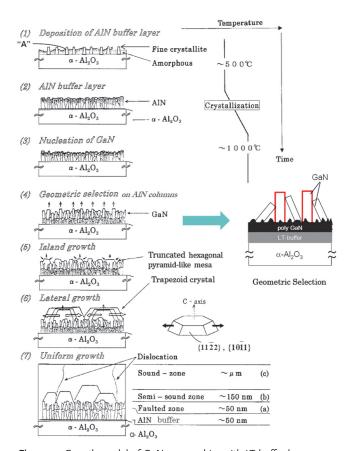


Figure 13. Growth model of GaN on sapphire with LT buffer layer. "Geometric selection" of the GaN fine crystals was suggested.

tilted or twisted at this stage in order to absorb the strain resulting from the large lattice mismatch. This suggests that geometric selection^[26] of the GaN fine crystals occurs, and the columnar fine GaN crystals increase accordingly in size during the growth, as shown in Figure 13(4). The number of columns emerging at the front gradually decrease with the front area of each column increasing accordingly. Because the only columns that survive are those that grow along the fastest growth directions, which is the c-axis, all columns eventually have their c-axis oriented normal to the substrate, as indicated by arrows in Figure 13 (4), which shows the growth model for GaN film on c-face sapphire with the LT-AlN buffer layer. In the faulted zone, trapezoidal islands are formed on top of the columnar crystals, as shown in Figure 11. At this stage, all of the columnar crystals are c-axis oriented, and this orientation is transferred to the trapezoidal islands, as shown in Figure 13(5). These islands preferentially grow to become lager trapezoid crystals, which cover the minor island nearby, and form the semi-sound zone.

Subsequently, "lateral growth and coalescence" of the islands occur in the stages shown in SEM images (3) and (4) in Figure 10 a. The trapezoid crystals grow at a higher rate in the lateral direction, as shown in image (6) in Figure 13, because the growth rate of the c-face is much lower. This lateral growth continues until the islands fully coalesce to form a continuous layer.

Since the crystallographic orientation of all of the islands is almost the same, a smooth well-oriented GaN layer with a low defect density is formed, as seen in Figure 8b. Thus, the uniform growth resulting from layer-by-layer growth leads to the sound zone.

On the other hand, in the case of direct growth without a LT buffer layer, hexagonal GaN columns with many different sizes and heights are formed. These grow three-dimensionally to result in a rough surface, and many pits at their boundaries, exposing the bare sapphire substrate, as shown in Figure 8a. The optimum thickness of the deposited AlN layer was found to be around 50 nm. If it was too thick (for example, 150 nm), the GaN film became polycrystalline. Also, if the deposition temperature of the AlN buffer layer was close to the temperature at which AlN crystals could be grown, the surface of GaN showed many hexagonal hillocks.^[23]

5. Discovery of p-Type GaN and Demonstration of p-n Junction Blue/UV LED

With the successful control of the quality of GaN, we could start working on p-type doping. Despite repeated efforts on Zn-doping of high-quality GaN films grown with a LT-AlN buffer layer, no successful results were obtained (although the film resistivity was increased). In 1988, Amano found that the Zn-related luminescence intensity was greatly increased with no change in spectral shape, when a high-quality Zn-doped GaN film was irradiated with low-energy electron-beam (LEEBI) at room temperature or lower.^[27] We suspected that the Fermi level of the sample was changed, which potentially led to a shift toward the p-type. However,



the samples did not exhibit p-type conduction. We then realized that Mg was a potentially shallower acceptor than Zn, as the difference in electronegativity between Mg and Ga is smaller than that between Zn and Ga. [28] In early 1989, graduate student Masahiro Kito carried out Mg doping of high-quality GaN grown by the LT buffer layer technology. For Mg doping, bis(cyclopentadienyl)magnesium (Cp₂Mg) or methyl-Cp₂Mg (MCp₂Mg) was used as a dopant precursor. [29,30]

Then we applied the LEEBI treatment to the sample, and found that the Mgrelated blue-luminescence intensity was markedly enhanced, while the spectral shape remained unchanged, and that the sample had been converted to low-resis-

tivity p-type crystal, as confirmed by measurements of the Hall effect^[2] and later the electron-beam-induced current (EBIC).^[31]

We immediately produced a high-performance GaN p-n junction blue/UV-LED with encouraging current-voltage (I-V) characteristics. This was demonstrated in 1989 and was the first such device in the world^[2] (Figure 14a,b). This LED exhibited blue light emission with a low current injection (<20 mA), and additional near UV light emission with a high current injection^[31] (Figure 14c).

As a possible mechanism for the LEEBI effect, we proposed the "Coulombic explosion" model. [32] In this model, electron-beam excitation generates many free electrons and holes (Coulombic explosion), which stimulate the breaking of Mg–H bonds, and create active Mg as an acceptor impurity. The validity of this mechanism was later confirmed by researchers at the University of Illinois, [33] and it was found to occur even at low temperatures. [27,33]

In 1992, S. Nakamura and his group obtained p-type GaN by thermal annealing above 400°C in a H₂-free atmosphere, rather than by electron irradiation of Mg-doped GaN using Cp₂Mg. It was clarified that the Mg becomes passivated by forming a Mg-H complex.^[34] To realize p-type nitrides, it is therefore essential to activate the Mg acceptor by releasing the hydrogen.^[35] Indeed, there is a high concentration of hydrogen atoms in MOVPE-grown nitrides. It should be noted, however, that the concentration of residual donors should be drastically reduced before solving problems related to hydrogen passivation of acceptors,^[36] which is also a well-known issue with regard to both III–V compounds and Si.

These results clearly show that improving the crystal quality by the LT buffer layer technology, Mg doping and its activation are the keys for the development of the p-type conduction in wide-bandgap nitrides.

We later went on to develop p-type nitride alloys; p-AlGaN in $1991-92^{[37]}$ and p-GaInN in $1995^{[38]}$ for the first time.

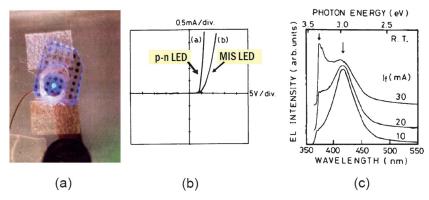


Figure 14. a) GaN p-n junction blue/UV LEDs (black dots). An electric current is only being passed through the centered LED that is emitting blue light. b) I–V characteristics of p-n junction LED (left) and MIS LED (right). c) EL spectra of GaN p-n junction blue/UV LED.

Conductivity Control of n-Type GaN and Nitride Alloys

Control of electric conductivity of n-type GaN grown without the LT buffer layer had been quite difficult, because of the high residual donor concentration of greater than 10^{19} cm⁻³. On the other hand, when a LT-AlN buffer layer was used, the conductivity of n-type GaN became extremely low because of the drastic reduction in the residual donor concentration. Control of n-type conductivity is extremely important for many types of nitride-based devices. In 1990, we succeeded in controlling the conductivity of n-type GaN^[3] (and AlGaN in 1991),^[39] over a range of about two orders of magnitude, by Si doping using SiH₄, as shown in Figure 15. High crystalline quality was again maintained by the use of the LT buffer layer technology.

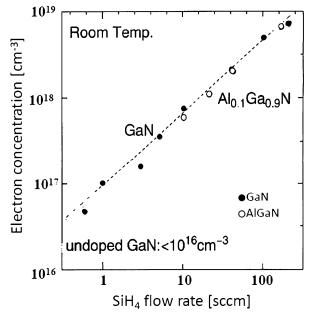


Figure 15. Electron concentrations in GaN (\bullet) and AlGaN (\circ) as a function of SiH₄ flow rate.



This conductivity-control method now enjoys widespread use around the world. The conductivity control of highquality p-type and n-type GaN and nitride alloys has allowed the use of heterostructure and multi-quantum wells (MQWs) for more efficient p-n junction light-emitting structures.

7. Brief History of Nitride-Based Blue LEDs

In 1992, we improved the external quantum efficiency of the blue/UV LED to 1.5% (power conversion efficiency of more than 1%) by employing an AlGaN/GaN double heterostructure (DH).[40] And in 1994, the first commercial AlGaN/GaInN:Zn,Si DH blue LED with the external quantum efficiency of 2.7% was launched.[41] In 1992, we also developed the first UV LEDs based on p-AlGaN/GaN/n-AlGaN DH with an output power of several mW at room temperature.[42]

Chronological developments in the external quantum efficiency, $\eta_{\rm ext}$, of nitride-based blue LEDs between 1971 and 2000 are shown in Figure 16. [43] It can be seen that $\eta_{\rm ext}$ was

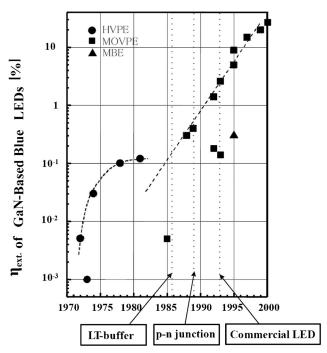


Figure 16. Chronological developments in external quantum efficiency, $\eta_{\rm ext}$ of nitride-based blue LEDs (1971–2000).

relatively constant at about 0.1%, before the breakthroughs described in this paper were achieved. It began to increase steeply soon after success was achieved in growing highquality nitride crystals, which resulted in the GaN p-n junction LED.^[2] To improve the emission efficiency of blue LEDs and the performance of violet LD, the use of GaInN alloy as an active layer is essential. The first successful growth of singlecrystal GaInN alloy was reported in 1989–1991. [44,45] Although it was soon used as the active layer of blue DH-LEDs, the devices functioned through donor-acceptor-pair emission rather than band-edge emission because of the low quality of GaInN. Growth of high-quality GaInN/GaN quantum wells (QWs)[46] and multiple QWs (MQWs)[47] exhibiting distinct band-edge emission, which is currently used as an active layer in blue LEDs, was first reported in 1995. In 2002, M. Yamada et al. reported that blue LEDs using such highquality GaInN/GaN MQWs exhibited a η_{ext} of higher than 36%. [48] They have been used as an excitation source for yellow phosphors in white LEDs.[49,50]

8. Development of Nitride-Based LDs and Other **Devices**

In 1990, we also succeeded for the first time in achieving room-temperature-stimulated emission in the UV range by optical excitation at a power that was one order of magnitude lower than that previously required, [51] showing that GaN is of high quality as shown previously. Figure 17[42,43] shows the

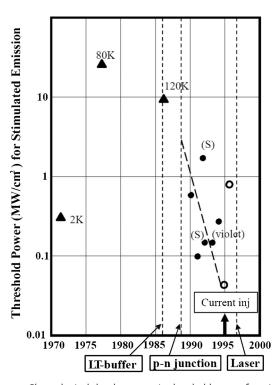


Figure 17. Chronological developments in threshold power for stimulated emission by optical pumping (before 1995) and current injection (after late 1995) from nitrides (1971-2000). ▲: stimulated emission (low temperature); ●: stimulated emission (room temperature); ○: laser action (room temperature); (S): surface mode.

threshold power, $P_{\rm th}$ for stimulated emission from nitrides over the years. Before 1986, stimulated emission with optical excitation could only be achieved at low temperatures and $P_{\rm th}$ was very high. We proposed that a significant reduction in $P_{\rm th}$ would be possible with the use of DHs or separate-confinement heterostructures (SCHs). This is due to the fact that the refractive index of the nitride system decreases with increasing bandgap energy.^[52] Similar to the increase in blue-LED efficiency shown in Figure 16, $P_{\rm th}$ began to decrease exponentially immediately after the marked improvement in the

7759



crystal quality of nitrides, described in the previous section. By optimizing the heterostructure, we obtained a new record of the lowest $P_{\rm th}$ almost every year between 1990 and 1995.

In 1995, we found that band-edge emission for GaInN/GaN MQWs with well widths of less than 3 nm, which roughly corresponds to the Bohr radius for excitons or electrons in GaN, was three orders of magnitude higher than that for a thick GaInN QW, as shown in Figure 18.^[53] In 1997, this

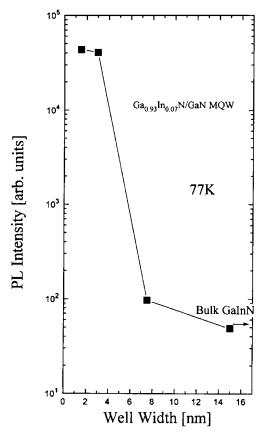


Figure 18. PL intensities (77 K) of GalnN/GaN QWs as a function of GalnN well width.

phenomenon was qualitatively attributed to suppression of the quantum-confined Stark effect (QCSE)^[54,55] in such narrow wells. The QCSE is caused by the presence of a large piezoelectric field^[54] in the GaInN well, which was found to be about 1 MV cm⁻¹ for an InN molar fraction of 0.1. By adopting such thin QWs as the active layer, we succeeded in demonstrating the first stimulated emission at 388 nm from a GaInN/GaN QW device with a well width of 2.5 nm under pulsed current injection at room temperature as shown in Figure 19.^[56]

Shortly after that, a group at Nichia Corporation reported a distinct pulsed lasing operation at 405 nm using an active layer composed of thin QWs.^[57] We achieved pulsed laser oscillations from a diode with a single quantum well at 376 nm in 1996^[58] and at 350.9 nm in 2004,^[59] which were the shortest wavelengths at the time. The first RT continuous-wave operation of a 405 nm blue-violet LD was reported in 1996,^[60] and such devices were later adapted as the light

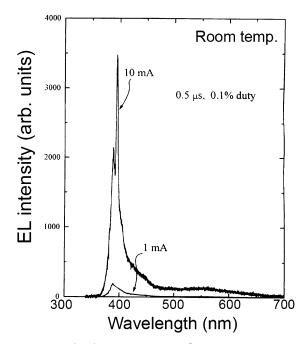


Figure 19. Stimulated emission spectrum from a GalnN/GaN QW device under pulsed current injection at room temperature.

source for high-density digital disk systems. In 2000, we developed a high-sensitivity solar-blind UV sensor with low dark current, [61] and in 2006 AlGaN/GaN heterostructure field-effect transistors with a high on-off ratio, low on-resistance, and normally-off mode. [62]

With regard to quantum effects in the nitride system, we verified the quantum size effect in 1991, [63] and the piezo-electric and quantum confined Stark effects in 1997, [54] as described above. In 2000, [64] Tetsuya Takeuchi et al. theoretically determined the orientation dependence of the piezo-electric field and showed the existence of non-/semipolar nitride crystal planes (see Figure 20). This has triggered world-wide efforts to grow such crystals in order to produce more efficient light emitters, such as high-efficiency green/

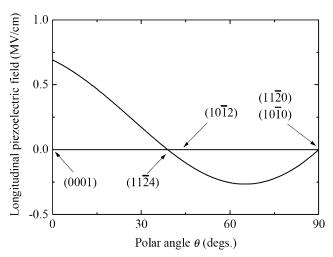


Figure 20. Calculated longitudinal piezoelectric field in strained $Ga_{0.9}In_{0.1}N$ on GaN as a function of the polar angle from (0001).



yellow-green LEDs,^[65] high-power blue-violet LEDs,^[66] and high-power green LDs.^[67]

9. Summary and Outlook

The creation of high-quality semiconductor-grade single crystals of GaN and related alloys, realization of low-resistivity p-type GaN, and conductivity control in n-type nitrides are all of great practical importance, and by 1991, these final pieces of the puzzle were in place. Stretching back to the late 1980s to the early 1990s, the remarkable achievements in GaN-based materials and devices have caught the eye of many scientists around the world, who become engaged in research in this field. Many topics relating to GaN-based LEDs and LDs have been published in scientific journals and presented at international conferences. Nitride research has become one of the most exciting themes in the world.

Turning back to Figure 3, it shows the number of publications per year referred to from INSPEC using the keywords GaN; major events in the history of nitride research are indicated. Events are labeled by the year when they were first achieved. As can be seen, the number of papers in 1969 is only four but it increased to 34 in 1975, inspired by the first GaN single crystal,^[11] the MIS LED,^[12] and stimulated emission from GaN at 2 K^[13] (period (A)).

The number then decreases until the year 1985, indicating that GaN research activity declined (period (B)), as the difficulty in achieving high-quality GaN and p-type conduction had been realized. However, after we succeeded in creating GaN single crystals with excellent quality (1986) and creating a GaN p-n junction blue/UV LED (1989), the number of published papers began to increase again. The number grew to 60 in 1991 after a short incubation period (period (C)), to 370 in 1995, to 1200 in 1997, and to 2040 in 2000 (period (D)).

At present, the aforementioned innovations of blue LEDs allow us to complete the set of three primary colors using semiconductors. Coupled with existing high-brightness red LEDs, blue/green LEDs are leading to the development of completely solid-state full-color displays, traffic lights, signals, signage, and specialized lighting applications. White LEDs composed of nitride-based blue/UV LEDs and yellow phosphor are two times more efficient than fluorescent lamps, and as such, white LEDs are now being used in TVs, mobile phones, computer displays, and general lighting equipment. The white and UV LEDs are expected to be used for biomedical applications, such as sterilization, microscopic level diagnoses, and medical treatments. Blue LEDs, combined with existing red LEDs are also being used for agricultural lighting sources. GaN-based LED lamps can operate for many hours on electricity produced by a solar battery, and can be used in places on Earth where there is no electrical power supply.

Long-lifetime nitride-based violet LDs are being used to read and write data in optical disc systems. Coupled with existing red LDs, GaN-based blue and green LDs are expected to be used in mini-projectors.

GaN-based group-III nitride semiconductors are also promising for high-speed/high-power electronic devices, as a result of their high electron saturation velocities and high breakdown voltages. Such devices are important in the mobile telecommunications industry, for energy saving in vehicles such as trains and automobiles, and also for home electrical appliances, such as air conditioners and refrigerators.

All of these nitride-based devices are robust in harsh environments, and allow a significant amount of energy to be saved, and provide a route to avoid the use of hazardous materials. The use of nitride-based devices will be one of our most powerful tools in the fight against global warming.

Acknowledgements

I wish to express my sincere appreciation to many collaborators: M. Hashimoto, Y. Ohki, Y. Toyoda, M. Ohshima, N. Mazda, H. Kobayasi, and M. Matsuki at Matsushita Research Institute Tokyo, Inc.; numerous students and co-researchers: N. Sawaki, K. Hiramatsu, Y. Koide, H. Amano, M. Kito, and H. Murakami at Nagoya University, and S. Kamiyama, T. Takeuchi, and M. Iwaya at Meijo University, and B. Monemar at Linköping/Lund Universities, for their great contributions throughout this research.

My special thanks is extended to Toyoda Gosei Company Ltd., Toyota Central Research Laboratory, and Japan Science and Technology Agency for their co-operation in the development and production of GaN-based blue LEDs and related materials.

This work received financial supports from the Ministry of International Trade and Industry, Japan (at that time), Ministry of Education, Culture, Sports, Science and Technology, Japan, and Japan Society for the Promotion of Science.

Finally, the author would like to thank the Nobel Foundation and members of the Royal Swedish Academy of Sciences for honoring our "invention of efficient blue-LEDs which has enabled the development of bright and energy-saving white light sources".

How to cite: *Angew. Chem. Int. Ed.* **2015**, *54*, 7750–7763 *Angew. Chem.* **2015**, *127*, 7860–7873

- [1] "Metalorganic vapor phase epitaxial growth of a high quality GaN film using an AlN buffer layer": H. Amano, N. Sawaki, I. Akasaki, Y. Toyoda, Appl. Phys. Lett. 1986, 48, 353.
- [2] "P-Type conduction in Mg-doped GaN treated with low-energy electron beam irradiation (LEEBI)": H. Amano, M. Kito, K. Hiramatsu, I. Akasaki, Jpn. J. Appl. Phys. 1989, 28, L2112.
- [3] "Fabrication and properties of GaN p-n junction LED": H. Amano, I. Akasaki, Ext. Abstr. Mater. Res. Soc. 1990, EA-21, 165.
- [4] "InGaN-based multi-quantum-well-structure laser diodes": S. Nakamura, M. Senoh, S. Nagahama, N. Iwasa, T. Yamada, T. Matsushita, H. Kiyoku, Y. Sugimoto, *Jpn. J. Appl. Phys.* 1996, 35, L74.
- "Coherent (visible) light emission from Ga(As_{1-x}P_x) junctions":
 N. Holonyak, Jr., S. F. Bevacqua, Appl. Phys. Lett. 1962, 1, 82.
- [6] "Efficient green electroluminescence in nitrogen-doped GaP pn junctions": R. A. Logan, H. G. White, W. Wiegman, Appl. Phys. Lett. 1968, 13, 139.



- [7] "SiC blue LEDs by liquid-phase epitaxy": H. Matsunami, M. Ikeda, A. Suzuki, T. Tanaka, IEEE Trans. Electron Devices 1977, 24, 958.
- [8] "p-type ZnSe by nitrogen atom beam doping during molecular beam epitaxial growth": R. M. Park, M. B. Troffer, C. M. Rouleau, J. M. DePuydt, M. A. Haase, *Appl. Phys. Lett.* 1990, 57, 2127.
- [9] "Blue-green laser diodes": M. A. Haase, J. Qiu, J. M. DePuydt, H. Cheng, Appl. Phys. Lett. 1991, 59, 1272.
- [10] "Infrared lattice vibration of vapor-grown AlN": I. Akasaki, M. Hashimoto, Solid State Commun. 1967, 5, 851 853.
- [11] "The preparation and properties of vapor-deposited singlecrystalline GaN": H. P. Maruska, J. J. Tietjen, *Appl. Phys. Lett.* 1969, 15, 327.
- [12] "GaN electroluminescent diodes": J. I. Pankove, E. A. Miller, J. E. Berkeyheiser, RCA Rev. 1971, 32, 383.
- [13] "Stimulated emission and laser action in gallium nitride": R. Dingle, K. L. Shaklee, R. F. Leheny, R. B. Zetterstrom, Appl. Phys. Lett. 1971, 19, 5.
- [14] "Refractive index of GaN": E. Ejder, *Phys. Status Solidi A* **1971**, **6**, 445.
- [15] "Fundamental energy gap of GaN from photoluminescence excitation spectra": B. Monemar, Phys. Rev. B 1974, 10, 676.
- [16] "Self-compensation limited conductivity in binary semiconductors. I. Theory": G. Mandel, Phys. Rev. 1964, 134, A1073.
- [17] "Fabrication and properties of a practical blue-emitting GaN mi-s diode": Y. Ohki, Y. Toyoda, H. Kobayasi, I. Akasaki, *Inst. Phys. Conf. Ser.* 1981, 63, 479.
- [18] "Breakthroughs in improving crystal quality of GaN and invention of the p-n junction blue-light-emitting diode": I. Akasaki, H. Amano, *Jpn. J. Appl. Phys. Part 1* 2006, 45, 9001; Erratum: I. Akasaki, H. Amano, *Jpn. J. Appl. Phys.* 2008, 47, 3781.
- [19] "The use of metalorganics in the preparation of semiconductor materials: IV. The nitrides of aluminum and gallium": H. M. Manasevit, F. M. Erdmann, W. I. Simpson, J. Electrochem. Soc. 1971, 118, 1864.
- [20] I. Akasaki, N. Sawaki, Jpn. Patent 1,708,203 (appl:1985.11.18), U.S. Patent 4,855,249; and later K. Manabe, H. Kato, I. Akasaki, K. Hiramatsu, H. Amano, Jpn. Patent 3,026,087 (appl:1989.3.1), U.S. Patent 5,122,845.
- [21] "Growth mechanism of GaN grown on sapphire with AlN buffer layer by MOVPE": K. Hiramatsu, S. Itoh, H. Amano, I. Akasaki, N. Kuwano, T. Shiraishi, K. Oki, J. Cryst. Growth 1991, 115, 628.
- [22] "Effects of AlN buffer layer on crystallographic structure and on electrical and optical properties of GaN and Ga_{1-x}Al_xN (0 < x ≤ 0.4) films grown on sapphire substrate by MOVPE": I. Akasaki, H. Amano, Y. Koide, K. Hiramatsu, N. Sawaki, J. Cryst. Growth 1989, 98, 209.</p>
- [23] "Effects of the buffer layer in metalorganic vapor phase epitaxy of GaN on sapphire substrate": H. Amano, I. Akasaki, K. Hiramatsu, N. Koide, N. Sawaki, *Thin Solid Films* 1988, 163, 415.
- [24] "Free excitons in GaN": B. Monemar, J. P. Bergman, I. A. Buyanova, W. Li, H. Amano, I. Akasaki, MRS Internet J. Nitride Semicond. Res. 1996, 1, 2.
- [25] "GaN growth using GaN buffer layer": S. Nakamura, Jpn. J. Appl. Phys. 1991, 30, L1705.
- [26] A. A. Chernov, Modern Crystallography III, Crystal Growth (Springer Series in Solid-State Science, Vol. 6, Springer, Berlin, 1984, p. 64.
- [27] "Electron beam effects on blue luminescence of zinc-doped GaN": H. Amano, I. Akasaki, T. Kozawa, K. Hiramatsu, N. Sawaki, K. Ikeda, Y. Ishii, J. Lumin. 1988, 40-41, 121.
- [28] J. C. Phillips, Bonds and Bands in Semiconductors, Academic Press, New York, London, 1973.
- [29] I. Akasaki, H. Amano, M. Kito, K. Hiramatsu, N. Sawaki, "Pureblue electroluminescence from Mg-doped GaN grown by

- MOVPE": Electrochem. Soc. 175th Meeting (SOTAPOCS-X) 673-SOA, 1989.
- [30] "Growth and luminescence properties of Mg-doped GaN prepared by MOVPE": H. Amano, M. Kitoh, K. Hiramatsu, I. Akasaki, J. Electrochem. Soc. 1990, 137, 1639.
- [31] "Photoluminescence of Mg-doped p-type GaN and electroluminescence of GaN p-n junction LED": I. Akasaki, H. Amano, M. Kito, K. Hiramatsu, J. Lumin. 1991, 48–49, 666.
- [32] "Measurement of the relative abundances and recoil-energy spectra of fragment ions produced as the initial consequences of X-ray interaction with CH₃I, HI, and DI": T. A. Carlson, R. M. White, J. Chem. Phys. 1966, 44, 4510.
- [33] "Time-dependent study of low energy electron beam irradiation of Mg-doped GaN grown by metalorganic chemical vapor deposition": X. Li, J. J. Coleman, Appl. Phys. Lett. 1996, 69, 1605.
- [34] "Thermal annealing effects on p-type Mg-doped GaN films": S. Nakamura, T. Mukai, M. Senoh, N. Iwasa, Jpn. J. Appl. Phys. 1992, 31, L139.
- [35] "Defeating compensation in wide gap semiconductors by growing in H that is removed by low temperature de-ionizing radiation": J. A. Van Vechten, J. D. Horning, B. Goldenberg, *Jpn. J. Appl. Phys.* 1992, 31, 3662.
- [36] "Hydrogen in Semiconductors II": Semiconductors and Semimetals, Vol. 61 (Ed.: N. H. Nickel), Academic Press, San Diego, 1999.
- [37] "Conductivity control of AlGaN. Fabrication of AlGaN/GaN multi-heterostructure and their application to UV/blue light emitting devices": I. Akasaki, H. Amano, *Mater. Res. Soc. Symp. Proc.* 1992, 242, 383 (Symposium held December 2–6, 1991, Boston).
- [38] "p-type conduction in Mg-doped Ga_{0.91}In_{0.09}N grown by metalorganic vapor-phase epitaxy": S. Yamasaki, S. Asami, N. Shibata, M. Koike, K. Manabe, T. Tanaka, H. Amano, I. Akasaki, Appl. Phys. Lett. 1995, 66, 1112.
- [39] "Growth of Si-doped Al_xGa_{1-x}N on (0001) sapphire substrate by metalorganic vapor phase epitaxy": H. Murakami, T. Asahi, H. Amano, K. Hiramatsu, N. Sawaki, I. Akasaki, J. Cryst. Growth 1991, 115, 648.
- [40] "GaN-based UV/blue light emitting devices": I. Akasaki, H. Amano, K. Itoh, N. Koide, K. Manabe, *Inst. Phys. Conf. Ser.* 1992, 129, 851.
- [41] "Candelaclass highbrightness InGaN/AlGaN double heterostructure blue light emitting diodes": S. Nakamura, T. Mukai, M. Senoh, Appl. Phys. Lett. 1994, 64, 1687.
- [42] "Room temperature ultraviolet/blue light emitting devices based on AlGaN/GaN multi-layered structure": I. Akasaki, H. Amano, Ext. Abstr. 24th Int. Conf. Solid State Devices Mater. 1992, 327.
- [43] "Crystal growth and conductivity control of group III nitride semiconductors and their application to short wavelength light emitters": I. Akasaki, H. Amano, *Jpn. J. Appl. Phys.* 1997, 36, 5393.
- [44] "Properties of Ga_{1-x}In_xN films prepared by MOVPE": T. Nagatomo, T. Kuboyama, H. Minamino, O. Otomo, *Jpn. J. Appl. Phys.* 1989, 28, L1334.
- [45] "Photoluminescence of InGaN films grown at high temperature by metalorganic vapor phase epitaxy": N. Yoshimoto, T. Matsuoka, T. Sasaki, A. Katsumi, Appl. Phys. Lett. 1991, 59, 2251
- [46] "Superbright green InGaN single-quantum-well-structure light-emitting diodes": S. Nakamura, M. Senoh, N. Iwasa, S. Nagahama, T. Yamada, T. Mukai, Jpn. J. Appl. Phys. 1995, 34, L1332.
- [47] "Fabrication and properties of GaN-based quantum well structure for short wavelength light emitter": H. Amano, I. Akasaki, Ext. Abstr. Int. Conf. Solid State Devices Mater. 1995, V-7, 683.
- [48] "InGaN-based near-ultraviolet and blue-light-emitting diodes with high external quantum efficiency using a patterned sapphire substrate and a mesh electrode": M. Yamada, T. Mitani, Y.



- Narukawa, S. Shioji, I. Niki, S. Sonobe, K. Deguchi, M. Sano, T. Mukai, Jpn. J. Appl. Phys. 2002, 41, L1431.
- [49] "Development of high-bright and pure-white LED lamp": K. Bando, K. Sakano, Y. Nobuchi, Y. Shimizu, J. Light Visual Environ. 1998, 22, 2.
- [50] Y. Shimizu, A. Banno, Jpn. Pat, 2,927,279, 1999 "Light-emitting diode [in Japanese]".
- [51] "Stimulated emission near ultraviolet at room temperature from a GaN film grown on sapphire by MOVPE using an AlN buffer layer": H. Amano, T. Asahi, I. Akasaki, Jpn. J. Appl. Phys. 1990, 29, L205.
- [52] "MOVPE growth of high quality $Al_xGa_{1-x}N/Ga_vIn_{1-y}N$ ($x \ge 0, y \le 1$ 1) heterostructure for short wavelength light emitter": I. Akasaki, H. Amano, Mater. Res. Soc. Symp. Proc. 1994, 339, 443.
- [53] I. Akasaki, H. Amano, I. Suemune, Inst. Phys. Conf. Ser. 1996,
- [54] "Quantum-confined stark effect due to piezoelectric fields in GaInN strained quantum wells": T. Takeuchi, S. Sota, M. Katsuragawa, M. Komori, H. Takeuchi, H. Amano, I. Akasaki, Jpn. J. Appl. Phys. 1997, 36, L382.
- [55] "Determination of piezoelectric fields in strained GaInN quantum wells using the quantum-confined Stark effect": T. Takeuchi, C. Wetzel, S. Yamaguchi, H. Sakai, H. Amano, I. Akasaki, Appl. Phys. Lett. 1998, 73, 1691.
- [56] "Stimulated Emission by Current Injection from an AlGaN/ GaN/GaInN Quantum Well Device": I. Akasaki, H. Amano, S. Sota, H. Sakai, T. Tanaka, M. Koike, Jpn. J. Appl. Phys. 1995, 34,
- [57] "InGaN-Based Multi-Quantum-Well-Structure Laser Diodes": S. Nakamura, M. Senoh, S. Nagahama, N. Iwasa, T. Yamada, T. Matsushita, H. Kiyoku, Y. Sugimoto, Jpn. J. Appl. Phys. 1996, 35,
- [58] "Shortest wavelength semiconductor laser diode": I. Akasaki, S. Sota, H. Sakai, T. Tanaka, M. Koike, H. Amano, Electron. Lett. **1996**, 32, 1105.
- [59] "350.9 nm UV laser diode grown on low-dislocation-density AlGaN": K. Iida, T. Kawashima, A. Miyazaki, H. Kasugai, S. Mishima, A. Honshio, Y. Miyake, M. Iwaya, H. Amano, I. Akasaki, Jpn. J. Appl. Phys. 2004, 43, L499.

- [60] "Room-temperature continuous-wave operation of InGaN multi-quantum-well structure laser diodes": S. Nakamura, M. Senoh, S. Nagahama, N. Iwasa, T. Yamada, T. Matsushita, Y. Sugimoto, H. Kiyoku, Appl. Phys. Lett. 1996, 69, 4056.
- [61] "Solar-blind UV photodetectors based on GaN/AlGaN p-in photodiodes": C. Pernot, A. Hirano, M. Iwaya, T. Detchprohm, H. Amano, I. Akasaki, Jpn. J. Appl. Phys. 2000, 39, L387.
- [62] "High on/off ratio in enhancement-mode Al_xGa_{1-x}N/GaN junction heterostructure field-effect transistors with p-type GaN gate contact": T. Fujii, N. Tsuyukuchi, M. Iwaya, S. Kamiyama, H. Amano, I. Akasaki, Jpn. J. Appl. Phys. 2006, 45, L1048.
- [63] "Metalorganic vapor phase epitaxial growth and properties of GaN/Al_{0.1}Ga_{0.9}N layered structures": K. Itoh, T. Kawamoto, H. Amano, K. Hiramatsu, I. Akasaki, Jpn. J. Appl. Phys. 1991, 30,
- [64] "Theoretical study of orientation dependence of piezoelectric effects in wurtzite strained GaInN/GaN heterostructures and quantum wells": T. Takeuchi, H. Amano, I. Akasaki, Jpn. J. Appl. Phys. 2000, 39, 413.
- [65] "High-efficiency single-quantum-well green and yellow-green light-emitting diodes on semipolar (2021) GaN substrates": S. Yamamoto, Y. Zhao, C. C. Pan, R. B. Chung, K. Fujito, J. Sonoda, S. P. DenBaars, S. Nakamura, Appl. Phys. Express 2010, 3, 122102.
- [66] "High-Power Blue-Violet Semipolar (2021) InGaN/GaN Light-Emitting Diodes with Low Efficiency Droop at 200 A cm⁻²": Y. Zhao, S. Tanaka, C. C. Pan, K. Fujito, D. Feezell, J. S. Speck, S. P. DenBaars, S. Nakamura, Appl. Phys. Express 2011, 4, 082104.
- [67] "High-power (over 100 mW) green laser diodes on semipolar {2021} GaN substrates operating at wavelengths beyond 530 nm": S. Takagi, Y. Enya, T. Kyono, M. Adachi, Y. Yoshizumi, T. Sumitomo, Y. Yamanaka, T. Kumano, S. Tokuyama, K. Sumiyoshi, N. Saga, M. Ueno, K. Katayama, T. Ikegami, T. Nakamura, K. Yanashima, H. Nakajima, K. Tasai, K. Naganuma, N. Fuutagawa, Y. Takiguchi, T. Hamaguchi, M. Ikeda, Appl. Phys. Express 2012, 5, 082102.

Received: March 23, 2015 Published online: May 27, 2015

7763